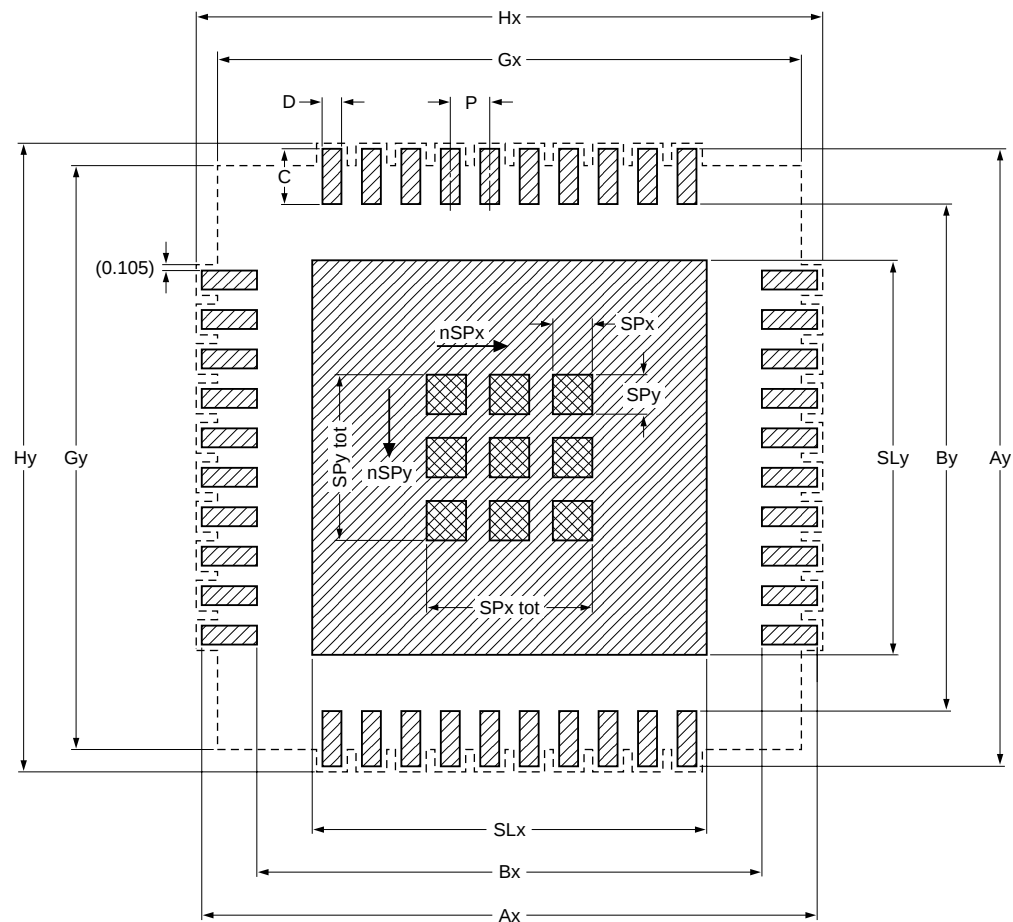


Footprint information for reflow soldering of DHVQFN24 package

SOT815-1



- Generic footprint pattern
Refer to the package outline drawing for actual layout
- solder land
 - solder paste deposit
 - solder land plus solder paste
 - occupied area

nSPx	nSPy
3	2

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	6.500	4.500	4.700	2.700	0.900	0.290	4.000	2.000	2.400	1.200	0.600	0.450	5.800	2.050	6.750	4.750